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Date: June 23, 2003

No. of Pages: 10 (including this cover sheet)

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Name: Commissioner of Patents

Art Unit: 2826

Examiner: Fetsum Abraham

Phone: (703) 305-3793

From: Daniel R. Kimbell
Reg No. 34,849Re: Application No. 09/383,150
Filed August 25, 1999Entitled **LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE INCORPORATING
MULTIPLE INTEGRATED CIRCUIT CHIPS, AND METHOD OF
FABRICATING A SEMICONDUCTOR CHIP...**

File: 35761/DBP/S295

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TECHNOLOGY CENTER 2800

I HEREBY CERTIFY THAT THIS PAPER IS BEING FACSIMILE TRANSMITTED TO
THE UNITED STATES PATENT AND TRADEMARK OFFICE ON June 23, 2003.
Elizabeth A. Jue

*Correspondence: Amendment Transmittal; Amendment After Final

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Return to Elizabeth A. JueChristie, Parker & Hale, LLP
350 West Colorado Boulevard
Post Office Box 7068
Pasadena, CA 91109-7068
626-795-9900
Fax: 626-577-8800**confidential**

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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL LETTER**

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Elizabeth A. Jue

Applicant : Rong-Fuh Shyu
Application No. : 09/383,150
Filed : August 25, 1999
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE
INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING
A SEMICONDUCTOR CHIP PACKAGE WITH MULTIPLE
INTEGRATED CIRCUIT CHIPS
Grp./Div. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

JUN 23 2003

Post Office Box 7068
Pasadena, CA 91109-7068
June 23, 2003

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Commissioner:

Enclosed is an amendment to the above-identified application.

CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Paid For	Number Extra Claims	Small Entity Rate	Large Entity Rate	FEE
Total Claims Fee	4	*20		x \$9.00	x \$18.00	
Independent Claims	1	** 3		x \$42.00	x \$84.00	
Multiple Dependent Claims ***				\$140.00	\$280.00	
TOTAL FILING FEE						0
NO ADDITIONAL FEE REQUIRED ****	IF NO FEE REQUIRED, INSERT "0"					0
LIST INDEPENDENT CLAIMS: 9						
* IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 20 OR LESS, WRITE "20" IN COLUMN 3 ** IF HIGHEST NUMBER PREVIOUSLY PAID FOR IS 3 OR LESS, WRITE "3" IN COLUMN 3 *** PAY THIS FEE ONLY WHEN MULTIPLE DEPENDENT CLAIMS ARE ADDED FOR THE FIRST TIME **** IF NO FEE REQUIRED, ADDRESS ENVELOPE TO "BOX NON-FEE AMENDMENTS"						

Amendment Transmittal Letter
Application No. 09/383,150

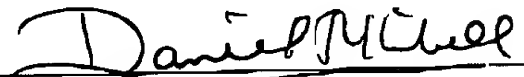
_____ Attached is our check for \$ to pay the fees calculated above.
_____ A Petition for Extension of Time and the required fee are enclosed.
_____ Other enclosures:

The Commissioner is hereby authorized to charge any fees under 37 CFR 1.16 and 1.17 which may be required by or to give effect to this paper to Deposit Account No. 03-1728. Please show our docket number with any charge or credit to our Deposit Account. **A copy of this letter is enclosed.**

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By


Daniel R. Kimbell
Reg. No. 34,849
626/795-9900

DRK/eaj

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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2826

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Elizabeth A. Jue
Elizabeth A. Jue

22/C
7-9-03
JSN

Appln No. : 09/383,150
Applicant : Rong-Fuh Shyu
Filed : August 25, 1999
Title : LEAD FRAME FOR A
SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE
INCORPORATING MULTIPLE
INTEGRATED CIRCUIT CHIPS, AND
METHOD OF FABRICATING A
SEMICONDUCTOR CHIP PACKAGE
WITH MULTIPLE INTEGRATED
CIRCUIT CHIPS
TC/A.U. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Post Office Box 7068
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June 23, 2003

Sir:

AMENDMENT AFTER FINAL

In response to the Office action of April 2, 2003, please
amend the above-identified application as follows:

Amendments to the Claims are reflected in the list of claims which
begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.